



**Minutes of P-3 Inductive Components Committee**

**Wednesday, 26 April, 2006 Sheraton Yankee Trader Hotel, Ft. Lauderdale, FL**

**Scope of the P-3 Committee on Inductive Devices:** "This committee covers all types of inductive components regardless of technology used in electronic circuits. It includes Inductors, RF Chokes, Filters, Interference Filters, Inductors and Transformers, Chip Inductors, and Variable Inductors."

Attendees:

<u>NAME</u>	<u>COMPANY</u>
Joe Biernacki	Stackpole
Phil Diglio	Epcos Inc
William Gisseler	TDK
Michael Griffith	KOA
Mike Lauri	IBM
Carl Lindquist	San-O Industrial Corp
Laird Macomber	Cornell Dubilier
Len Metzger	Panasonic
Ed Mikoski	EIA/ECA

<u>Member Organizations Present</u>	<u>Present this meeting</u>	<u>Present Memphis</u>	<u>Present New Orleans</u>
Cornell Dubilier	Y	N	Y
Epcos Inc	Y	Y	Y
IBM	Y	Y	Y
KOA	Y	Y	Y
Panasonic	Y	Y	Y
San-O-Industrial Corp	Y	N	Y
Stackpole	Y	Y	n/a
TDK	Y	Y	Y

**^Indicates activated as member of committee  
62189:8/06**

<u>Member Organizations Absent</u>	<u>Present at This Meeting?</u>	<u>Present Memphis</u>	<u>Present New Orleans</u>
Yageo	N	N	Y

\* Indicates not used in determination of quorum due to record of non-attendance

<u>Other Organizations Present</u>
EIA/ECA

## 1.0 Committee Organization and Procedures

Meeting was brought to order by Chairman Bill Gisseler @ 8:00 am  
 Membership & attendance – Sign-in sheet was circulated A quorum was present.

1.1 Next the minutes from the Fall 2005 meeting was reviewed and a motion was made and seconded to approve the minutes with an amendment to include all members that attended prior meetings. A motion was made and carried to accept the amended minutes.

1.2 The Agenda for this meeting was reviewed and accepted as presented.

1.3 Received E-mail from Mike Griffith from a customer on standardized marking the manufacturers in attendance agreed that this would be extremely difficult given the varieties of marking styles available.

## 2.0 Old Business:

2.1 Again review Test Procedures and recommended electrical parameters, per the Fall '05 meeting- Data was submitted by IBM, TDK, Panasonic, EPCOS, KOA, and IBM. It was agreed to use this data as the basis to see if there is some consistency. A discussion ensued and it was agreed that the inputs from the manufacturers was not broad enough to make a usable table and too many variations exist and maybe this should not be called out in the Inductors specs. Chairman Gisseler will again send to the group the combined inputs for another review and final specs discussion at the next meeting.

2.2 EIA/ECA - Survey of users- this will be if there is some recommendation by the group at the next meeting to point 2.1 -same as 2.1, but users side

2.3 Review package size and Pad layouts - - Still waiting for adoption and by the P-4 group – for review at the Fall session E-mail correspondence was discussed and it was decided that if a reply is not made in 30 days, that it is either assumed that there is agreement with the proposal and/or a comment made after that 30 days the input will not be considered

#### 2.4 EIA-958 (PN-5104) Surface Mount Common Mode Chokes

2.4.1 - Ballot sent and results received from IBM, San-O Ind., KOA, TDK. Missing – Epcos and Panasonic

2.4.2 - Comments – None

2.4.3 - A motion was made to send a clean copy of spec to ECA for publication

#### 2.5 Explore development of Marketing report for all Inductors by type ( Similar to capacitors)

2.5.1 - PCMC is a council that could do this and Inductor Manufacturers will be solicited..

2.5.2 - Target is to have participation by Fall of 2006. Companies in attendance were favorable. Report would be quarterly, Coilcraft, Epcos and TDK were in agreement to supply this data. Report format will be similar to the world-wide capacitor group.

2.5.3 - What can the P-3 group do to assist in the process. Like categories, sizes, etc... Bill Gisseler to make contact with the PCMC for details on how to participate.

### **3.0 New business and opportunities:**

3.1 Discuss putting together a standard for Power Inductors group referred this back to user's group. Mike Lauri of IBM will provide some inputs on what users would want to see in a spec., all points below 3.1.1 through 3.1.8 - users side. Mike Lauri to provide a qual standard used by IBM

3.1.1 - Components to consider:

3.1.2 - Mechanical sizes, pad layouts?

3.1.3 - Shielded vs. Non-Standard

3.1.4 - Inductance ranges and tolerances

3.1.5 - Current ranges, saturation

3.1.5.1 - Delta L, or I, etc..

3.1.5.2 - temperature rise

3.1.6 - Rdc

3.1.7 - Impedance

3.1.8 - Temperature ranges

3.1.9 - Anything additional from the customer's side.

### 3.2 Other New Business or Activities

3.2.1 - Ideas to recruit User's to meetings? This will also be addressed in All-Chair meeting.

3.2.2 - Additional New Topics or subjects for discussion - None

### 4.0 Next Meeting

September 25th - 29th, 2006 - Reno, NV

### 5.0 Adjournment

Motion made, seconded and carried to adjourn – 9:30am

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

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Bill Gisseler  
Chairman

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Phil Diglio  
Secretary